03 February 2004

L Number	Hits	Search Text	DB	Time stamp
_	9449	205/\$.ccls. and (microelectronic or circuit or wafer	USPAT;	2004/02/02
		or electronic or semiconductor)	US-PGPUB;	11:36
		÷	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	5847	(205/\$.ccls. and (microelectronic or circuit or wafer	USPAT;	2004/02/02
		or electronic or semiconductor)) and (via or aperture	US-PGPUB;	11:37
		or throughhole or hole or opening or trench)	EPO; JPO;	
			DERWENT;	
;		·	IBM_TDB	
_	1	045245.apn.	USPAT;	2004/02/02
		· '	US-PGPUB;	14:16
		·	EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
_	2	6197181.pn.	USPAT;	2004/02/02
			US-PGPUB; 14:19	14:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2	6113771.pn.	USPAT,	2004/02/02
			US-PGPUB;	14:19
			EPO; JPO;	
		†	DERWENT;	
			IBW_TDB	
-	2	6375731.pn.	USPAT;	2004/02/03
			U5-PGPUB;	10:07
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3231	205/81,82,84,118,123,125,126,183,205,210,219,291.ccl		2004/02/03
		·	US-PGPUB;	10:08
			EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	3300	205/81,82,84,118,123,125,126,183,205,210,215,219,29		2004/02/03
			US-PGPUB;	10:08
		·	EPO; JPO;	
			DERWENT;	
	-		IBM_TDB	
-	44	((205/\$.ccls. and (microelectronic or circuit or wafer	USPAT;	2004/02/03
		or electronic or semiconductor)) and (via or aperture	US-PGPUB;	10:09
	1	or throughhole or hole or opening or trench)) and	EPO; JPO;	
		((test\$5 or check\$5 or analy\$7) with (void\$5 or	DERWENT;	
		discontin\$))	IBM_TDB	<u> </u>

•	0	(205/81,82,84,118,123,125,126,183,205,210,215,219,29	1.6BAT;	2004/02/03
		and (microelectronic or circuit or wafer or electronic	US-PGPUB;	10:09
		or semiconductor) and (via or aperture or throughhole	EPO; JPO;	
		or hole or opening or trench) and ((test\$5 or	DERWENT;	į
		check\$5 or analy\$7) with (void\$5 or discontin\$)))	IBM_TDB	
		not (((205/\$.ccls. and (microelectronic or circuit or		
		wafer or electronic or semiconductor)) and (via or		
		aperture or throughhole or hole or opening or		
		trench)) and ((test\$5 or check\$5 or analy\$7) with		
	13	@@ 5d\$5,82,di &dd6t1&\$)}}\$5,126,183,205,210,215,219,293	.dd&PAT	2004/02/03
		and (microelectronic or circuit or wafer or electronic	US-PGPUB;	10:09
		or semiconductor) and (via or aperture or throughhole	EPO; JPO;	
		or hole or opening or trench) and ((test\$5 or	DERWENT;	
	·	check\$5 or analy\$7) with (void\$5 or discontin\$))	IBM_TDB	